

FEATURES

- 150Watts peak pulse power ($t_p = 8/20\mu s$)
- Protects One Power or I/O Port
- Low leakage current
- Working voltages : 24 V
- Low operating and clamping voltages
- Solid-state silicon avalanche technology

APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Portable Instrumentation
- Personal Digital Assistant(PDA)



SOD-523



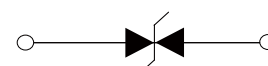
Marking

IEC COMPATIBILITY

- IEC61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- RoHS** Compliance with 2011/65/EU
- HF** Compliance with IEC61249-2-21:2003



Schematic Symbol

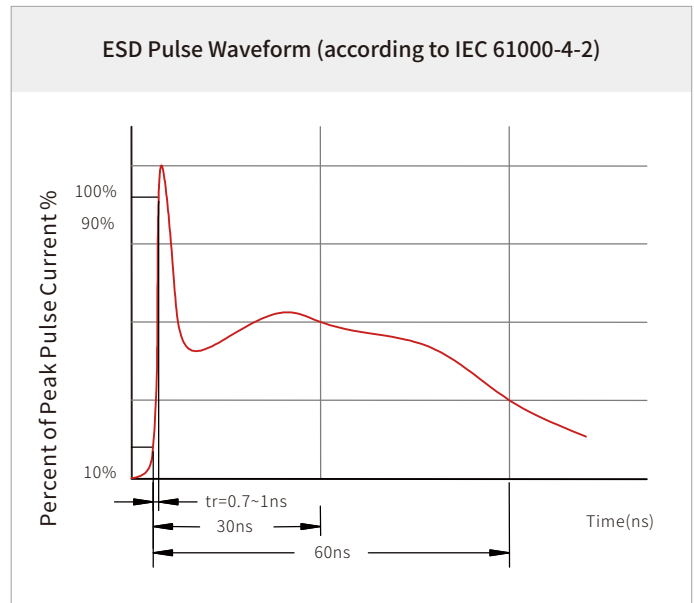
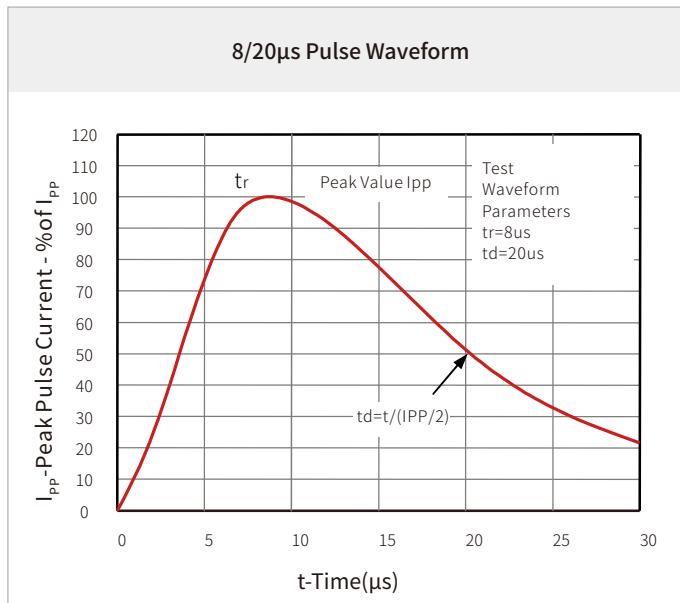
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{pp}	Peak Pulse Power ($t_p=8/20\mu s$ waveform)	150	Watts
T_J	Operating Temperature Range	-55 to +125	$^{\circ}C$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}C$

ELECTRICAL CHARACTERISTICS

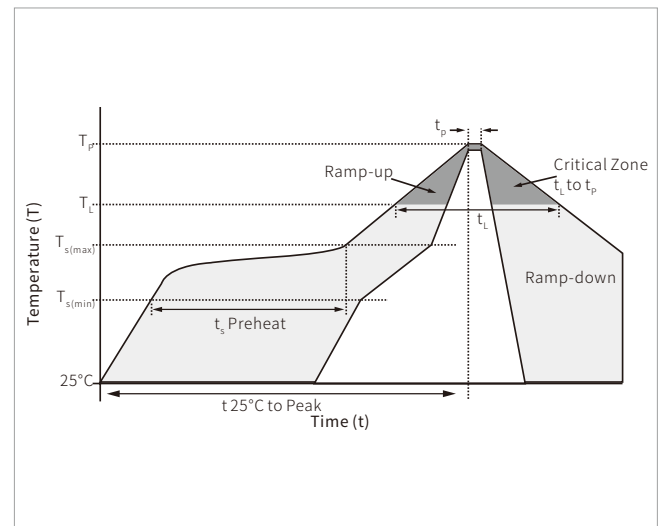
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	26.1			V
I_R	Reverse Leakage Current	$V_{RWM}=24V$			1	μA
V_C	Clamping Voltage	$I_{pp}=1A, t_p=8/20\mu s$			44	V
V_C	Clamping Voltage	$I_{pp}=3A, t_p=8/20\mu s$			54	V
I_{PP}	Peak Pulse Current	$t_p=8/20\mu s$			3	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$			30	pF

CHARACTERISTIC CURVES

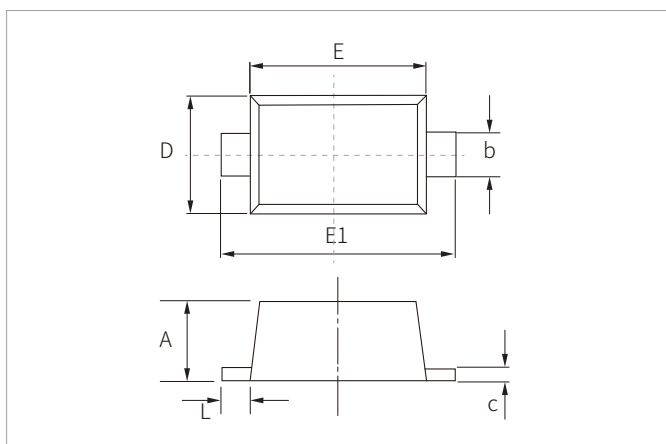


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

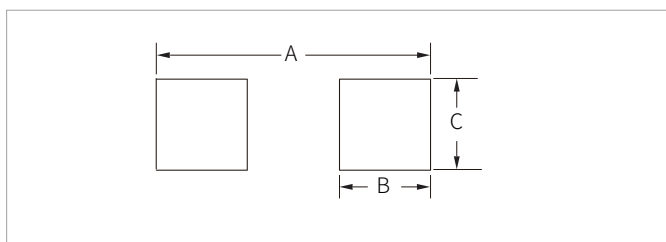


SOD-523 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.50	0.80	0.020	0.031
b	0.25	0.35	0.010	0.014
c	0.07	0.20	0.003	0.008
D	0.70	0.90	0.028	0.035
E	1.10	1.30	0.043	0.051
E1	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
	Min.	Min.
A	2.00	0.0787
B	0.60	0.0236
C	0.70	0.0276

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE5D15B24A	SOD-523	3000PCS	7"

Headquarters

No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline

400-021-5756

Web

<https://www.semiware.com>

Sales Center

Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

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